BES2700iMP

Brief Datasheet

Ultra-low Power Bluetooth Wearable Platform

CONTACT US:

Company: *Bestechnic (Shanghai) Co., Ltd. ("**BES**")*

Address: *2F, Building B, Lane 2889 Jinke Road, Pudong, Shanghai (201203)*

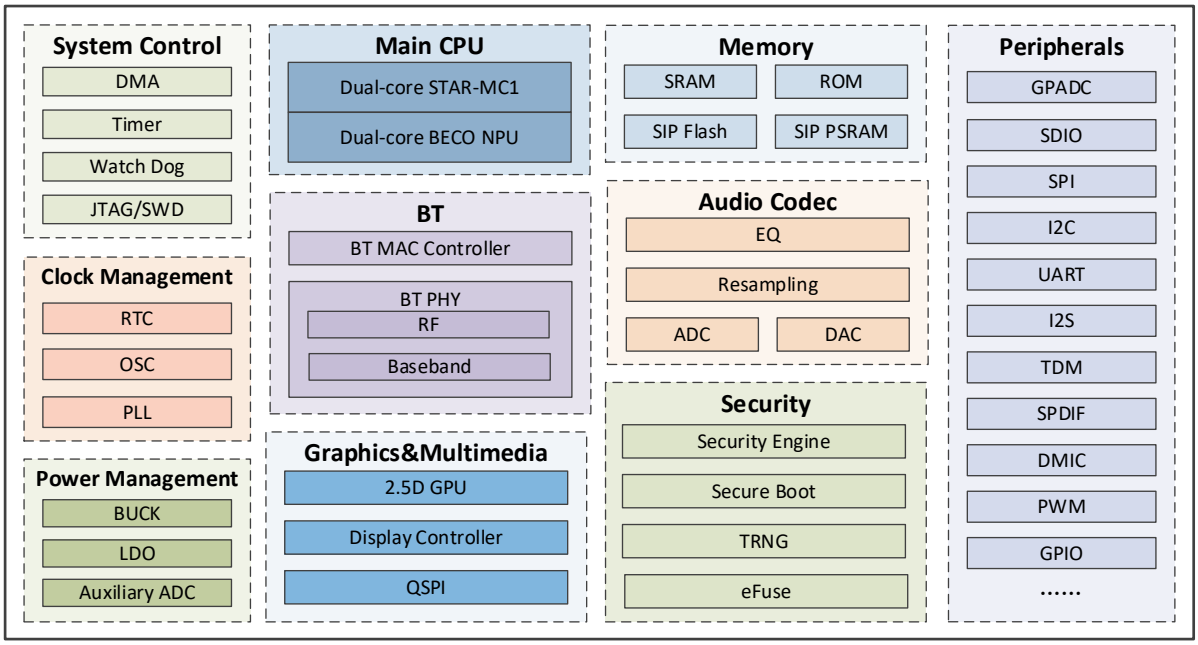
Phone: *(86)21 6877 1788*

For product inquiries and more information, please visit www.bestechnic.com*.*

1 General Description

The BES2700iMP is an ultra-low power, high performance Bluetooth wearable SoC. The platform incorporates a high performance CPU subsystem comprising a dual-core STAR-MC1 processor with a dual-core BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, RAM/ROM, PSRAM and flash for software features and product customization, as well as a variety of interfaces. This combination minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth wearable solution.

The platform incorporates a dual-mode Bluetooth 5.4 subsystem, a codec subsystem and a graphics subsystem that includes a 2.5D GPU for advanced graphics features and an LCD controller with up to 3-layer alpha blending. It also integrates a Power Management Unit (PMU).



System Block Diagram

1.1 Applications

- Sports watches
- Smart watches
- Bluetooth wristbands
- Other wearable devices

1.2 Features & Specifications*

CPU Subsystem	Dual-core STAR-MC1
Memory and Storage	Shared 1.4 MB SRAM
	Flash and PSRAM in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.4 with LE audio
Graphics & Multimedia	2.5D Vector GPU
	MIPI DSI
Audio & Voice Features	1x DAC
	2x ADCs
Peripheral Interfaces	GPADC/SDIO/SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/PWM/GPIO……
Package	170-pin BGA

* The content in the table is subject to change without notice.